## Advance Product Change Notification | 201404006A

**Issue Date:**      14-Apr-2014

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# QUALITY

### Change Category

[ ] Wafer Fab process       [ ] Assembly Process       [ ] Product Marking                  [X] Design
[ ] Wafer Fab materials     [ ] Assembly Materials     [ ] Electrical spec./Test coverage   [ ] Mechanical Specification
[ ] Wafer Fab location      [ ] Assembly Location      [ ] Test Location                    [ ] Packing/Shipping/Labeling

## Qualification of D4 R0-clip overhang removal for a subset of LFPAK devices

### Details of this Planned Change

The shape of the source clip on a small range of LFPAK device types is to be optimised. It will be reduced in overall dimension to make it smaller in size than the die size.

**Why do we Plan this Change**

Recent reliability studies on LFPAK device types have highlighted a low line PPM risk with the current clip. The optimised source clip is to be made to eliminate the failure mode, in line with NXP's Zero Defects policy.

**Identification of Affected Products**

Product identification does not change

### Product Availability

**Sample Information**

Samples are available from 25-Aug-2014

**Production**

Planned first shipment 06-Oct-2014

## Impact

no impact to the product's functionality anticipated.

**Data Sheet Revision**

No impact to existing datasheet

**Disposition of Old Products**

Existing inventory will be shipped until depleted

## Additional information

Affected products and sales history information
Self qualification _____

## Timing and Logistics

The Self Qualification Report will be ready on 25-Aug-2014.
The Final PCN is planned to be issued on: 25-Aug-2014.
Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 14-May-2014.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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